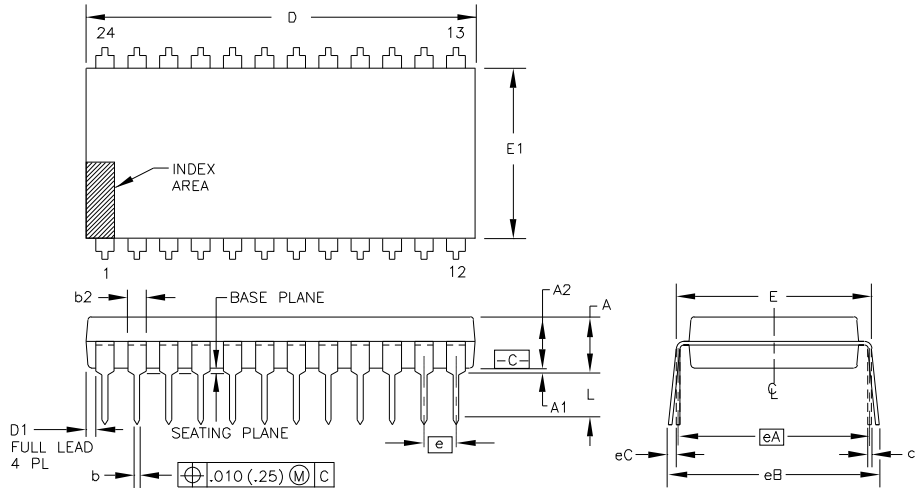


Package Number 167 - 24-Pin Plastic Double-Wide DIP



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	--	.250	--	6.35	3		L	.115	.200	2.92	5.08	3	
A1	.015	--	0.38	--	3		N	24	24			7	
A2	.125	.195	3.18	4.95									
b	.014	.022	0.36	0.56									
b2	.030	.070	0.76	1.78	9								
c	.008	.015	0.20	0.38									
D	1.150	1.290	29.21	32.77	4								
D1	.005	--	0.13	--	4								
E	.600	.625	15.24	15.88	5								
E1	.485	.580	12.32	14.73	4								
e	.100	BASIC	2.54	BASIC									
eA	.600	BASIC	15.26	BASIC	5								
eB	--	.700	--	17.78	6								
eC	.000	.060	0.00	1.52	6								

NOTES:

1. ALL DIMENSIONS ARE IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
3. DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
5. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM ---C--- .
6. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. N IS THE MAXIMUM OF TERMINAL POSITIONS.

8. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
9. b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
10. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
11. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
12. FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.

PACKAGE NUMBER: ZZ167 REV.: H
 JEDEC NUMBER: MS-011-AA



PACKAGE DRAWING

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